

SLOVENSKI STANDARD

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SIST EN 60068-2-58:2005

Okoljsko preskušanje - 2-58. del: Preskusi - Preskus Td: preskusna metoda za spajkanje, odpornost površinsko montiranih komponent (SMD) proti razkrajanju pokovinjena in vročini spajke

Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)

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Umweltprüfungen - Teil 2-58: Prüfungen - Prüfung Td: Prüfverfahren für Lötbarkeit, Widerstandsfähigkeit gegenüber Auflösen der Metallisierung und Lötwärmebeständigkeit bei oberflächenmontierbaren Bauelementen (SMD)

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Essais d'environnement - Partie 2-58: Essais - Essai Td: Méthodes d'essai de la soudabilité, résistance de la métallisation à la dissolution et résistance à la chaleur de brasage des composants pour montage en surface (CMS)

Ta slovenski standard je istoveten z: EN 60068-2-58:2015

ICS:

19.040 Preskušanje v zvezi z Environmental testing
okoljem

31.190 Sestavljeni elektronski Electronic component
elementi assemblies

SIST EN 60068-2-58:2015

en

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EUROPEAN STANDARD

EN 60068-2-58

NORME EUROPÉENNE

EUROPÄISCHE NORM

May 2015

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Supersedes EN 60068-2-58:2004

English Version

**Environmental testing - Part 2-58: Tests - Test Td: Test methods
for solderability, resistance to dissolution of metallization and to
soldering heat of surface mounting devices (SMD)
(IEC 60068-2-58:2015)**

Essais d'environnement - Partie 2-58: Essais - Essai Td:
Méthodes d'essai de la soudabilité, résistance de la
métallisation à la dissolution et résistance à la chaleur de
brasage des composants pour montage en surface (CMS)
(IEC 60068-2-58:2015)

Umweltprüfungen - Teil 2-58: Prüfungen - Prüfung Td:
Prüfverfahren für Lötbarkeit, Widerstandsfähigkeit
gegenüber Auflösen der Metallisierung und
Lötwärmebeständigkeit bei oberflächenmontierbaren
Bauelementen (SMD)
(IEC 60068-2-58:2015)

This European Standard was approved by CENELEC on 2015-05-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

Foreword

The text of document 91/1222/FDIS, future edition 4 of IEC 60068-2-58, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60068-2-58:2015.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2016-02-01
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2018-05-01

This document supersedes EN 60068-2-58:2004.

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The text of the International Standard IEC 60068-2-58:2015 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-2-54	NOTE	Harmonized as EN 60068-2-54.
IEC 60068-2-69	NOTE	Harmonized as EN 60068-2-69.
IEC 60749-20	NOTE	Harmonized as EN 60749-20.
IEC 61760-3	NOTE	Harmonized as EN 61760-3.
IEC 61760-4	NOTE	Harmonized as EN 61760-4 ¹⁾ .

1) To be published.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-1	-	Environmental testing - Part 1: General and guidance	EN 60068-1	-
IEC 60068-2-20	2008	Environmental testing - Part 2-20: Tests - Test T: Test methods for solderability and resistance to soldering heat of devices with leads	EN 60068-2-20	2008
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	EN 60194	-
IEC 61190-1-1	-	Attachment materials for electronic assembly - Part 1-1: Requirements for soldering fluxes for high-quality interconnections in electronics assembly	EN 61190-1-1	-
IEC 61190-1-2	2014	Attachment materials for electronic assembly - Part 1-2: Requirements for soldering pastes for high-quality interconnects in electronics assembly	EN 61190-1-2	2014
IEC 61190-1-3 + A1	2007 2010	Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications	EN 61190-1-3 + A1	2007 2010
IEC 61191-2	-	Printed board assemblies - Part 2: Sectional specification - Requirements for surface mount soldered assemblies	EN 61191-2	-

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61249-2-22	-	Materials for printed boards and other interconnecting structures - Part 2-22: Reinforced base materials, clad and unclad - Modified non-halogenated epoxide woven E-glass laminated sheets of defined flammability (vertical burning test), copper-clad	EN 61249-2-22	-
IEC 61249-2-35	-	Materials for printed boards and other interconnecting structures - Part 2-35: Reinforced base materials, clad and unclad - Modified epoxide woven E-glass laminate sheets of defined flammability (vertical burning test), copper-clad for lead-free assembly	EN 61249-2-35	-
IEC 61760-1	-	Surface mounting technology - Part 1: Standard method for the specification of surface mounting components (SMDs)	EN 61760-1	-
ISO 9454-2	1998	Soft soldering fluxes - Classification and requirements - Part 2: Performance requirements	EN ISO 9454-2	2000

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INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Environmental testing –
Part 2-58: Tests – Test Td: Test methods for solderability, resistance to
dissolution of metallization and to soldering heat of surface mounting devices
(SMD)**

[SIST EN 60068-2-58:2015](https://standards.iteh.ai/catalog/standards/sist/37af21f9-557c-4545-8c55-f7fb6838563c/sist-en-60068-2-58-2015)

[https://standards.iteh.ai/catalog/standards/sist/37af21f9-557c-4545-8c55-](https://standards.iteh.ai/catalog/standards/sist/37af21f9-557c-4545-8c55-f7fb6838563c/sist-en-60068-2-58-2015)

Essais d'environnement –

**Partie 2-58: Essais – Essai Td: Méthodes d'essai de la soudabilité, résistance de
la métallisation à la dissolution et résistance à la chaleur de brasage des
composants pour montage en surface (CMS)**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

ENVIRONMENTAL TESTING –

**Part 2-58: Tests –
Test Td: Test methods for solderability, resistance
to dissolution of metallization and to soldering heat
of surface mounting devices (SMD)**

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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International Standard IEC 60068-2-58 has been prepared by IEC technical committee 91: Electronics assembly technology.

This fourth edition cancels and replaces the third edition, published in 2004 and constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- the addition of Sn-Bi low temperature solder alloy;
- the addition of several reflow test conditions in Table 7 – Resistance to soldering heat – Test conditions and severity, reflow method;
- introduction of reflow test method for Test Td₃: Dewetting and resistance to dissolution of metallization;

– implementation of guidance for the choice of a test severity in Clause B.3.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/1222/FDIS	91/1250/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60068, published under the general title *Environmental testing*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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ENVIRONMENTAL TESTING –

Part 2-58: Tests – Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)

1 Scope

This part of IEC 60068 outlines test Td, applicable to surface mounting devices (SMD).

This standard provides procedures for determining the solderability and resistance to soldering heat of devices in applications using solder alloys, which are eutectic or near eutectic tin lead (Pb), or lead-free alloys.

The procedures use either a solder bath or reflow method and are applicable only to specimens or products designed to withstand short term immersion in molten solder or limited exposure to reflow systems.

The solder bath method is applicable to SMDs designed for flow soldering and SMDs designed for reflow soldering when the solder bath (dipping) method is appropriate.

The reflow method is applicable to the SMD designed for reflow soldering, to determine the suitability of SMDs for reflow soldering and when the solder bath (dipping) method is not appropriate.

The objective of this standard is to ensure solderability of component lead or termination. In addition, test methods are provided to ensure that the component body can resist against the heat load to which it is exposed during soldering.

This standard covers tests Td₁, Td₂ and Td₃ as listed below:

Number of Td	Test	Method
Td ₁	Solderability of terminations	Method 1: Solder bath Method 2: Reflow
Td ₂	Resistance to soldering heat	Method 1: Solder bath Method 2: Reflow
Td ₃	Dewetting and resistance to dissolution of metallization	Method 1: Solder bath Method 2: Reflow

NOTE 1 For specific components other test methods may exist.

NOTE 2 Test Td does not apply to printed wiring board (PWB), see IEC 61189-3.

NOTE 3 Specific through-hole devices (where the device supplier has specifically documented support for reflow soldering) are also included in this standard.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-1, *Environmental testing – Part 1: General and guidance*

IEC 60068-2-20:2008, *Environmental testing – Part 2-20: Tests – Test T: Test methods for solderability and resistance to soldering heat of devices with leads*